Product Specification

Product:	**Encapsulation Paste**
Part Number:	**07M-SL31**

Application Scope :

This paste is suitable for encapsulation of thick-film circuits.

Usage Conditions :

Substrate	Thick-film circuit, alumina ceramic
Usage Method	Printing, 200-250 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 550±10°C (recommended value) for 10 minutes in the atmosphere of the tunnel furnace. The sintering range can be adjusted within 530-650°C as needed, but the peak temperature must be maintained for 10 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤8μm	FOG test
2	Viscosity	100~200Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R), 10 rpm, 25±1°C
3	Appearance	**Transparent, Black, Blue, Green**	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1）

Characteristics		Standard	Test Method And Conditions
4	Appearance	Compact and dense	Visual inspection & microscopy

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.